



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

▶ Domestic Part Number	EV-IRF540NS-T2
▶ Overseas Part Number	IRF540NS
▶ Equivalent Part Number	IRF540NS

"T2" means TO-263



EV is the abbreviation of name EVVO

# EV-IRF540NS-T2

- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Green Device Available
- ★ Advanced high cell density Trench technology

## Product Summary

BVDSS	RDS(on)	ID
100V	47mΩ	27A

## Description

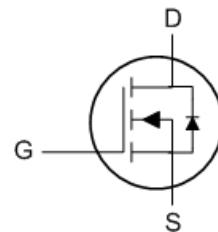
The EV-IRF540NS-T2 is the high cell density trenched

N-ch MOSFETs which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The EV-IRF540NS-T2 meet the RoHS and Green Product

requirement, 100% EAS guaranteed with full function reliability approved.

## TO263 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	27	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	17	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4.2	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.3	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	54	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	36.5	mJ
I <sub>AS</sub>	Avalanche Current	27	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	87	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	1.44	°C/W

**N-Ch 100V Fast Switching MOSFETs**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

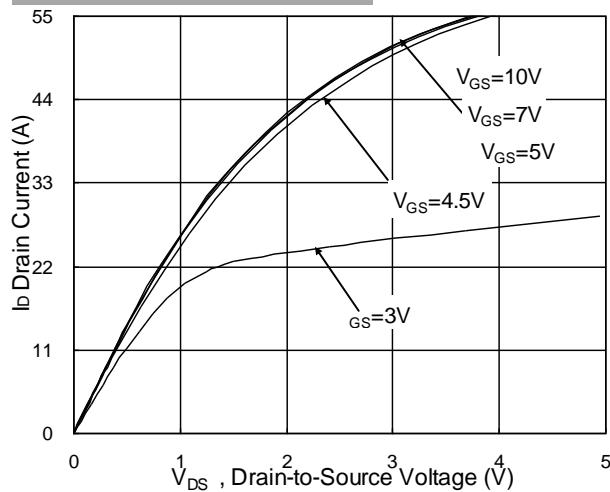
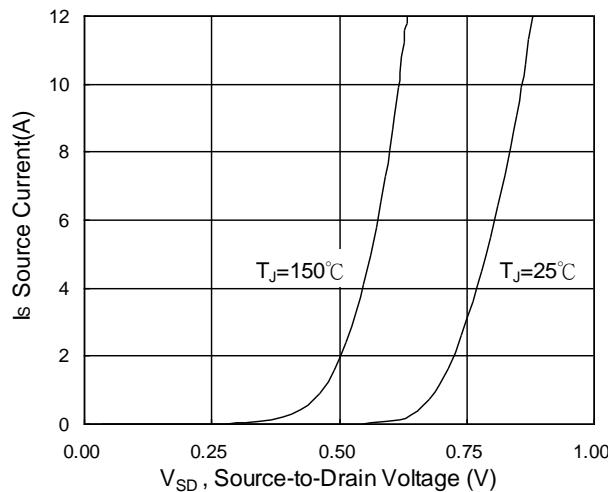
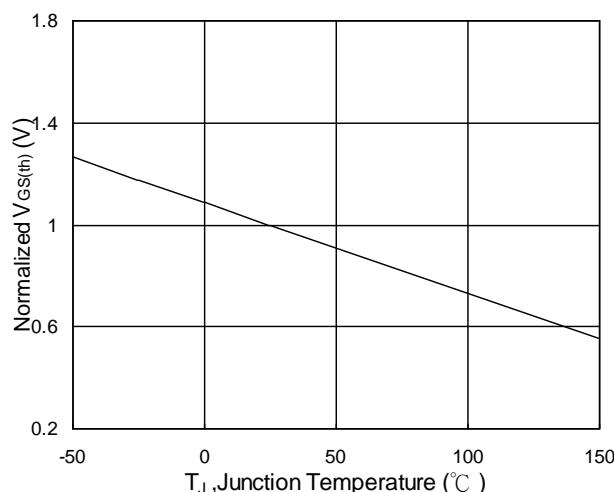
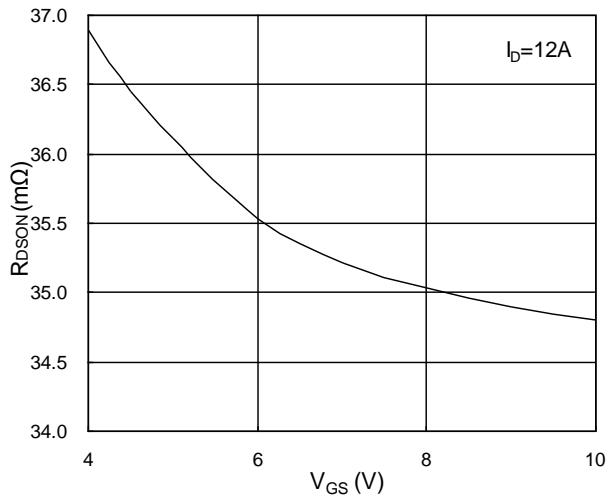
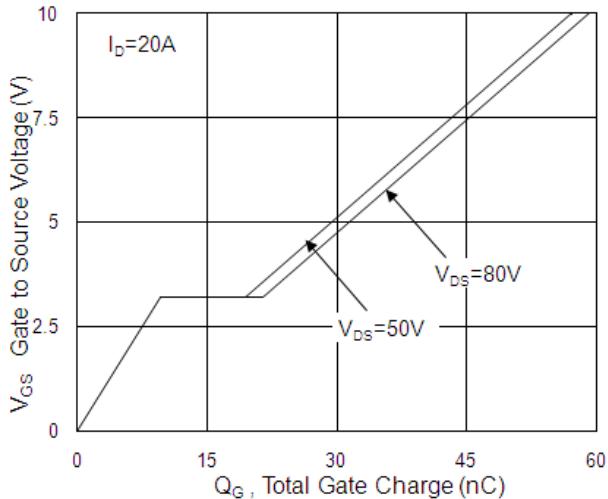
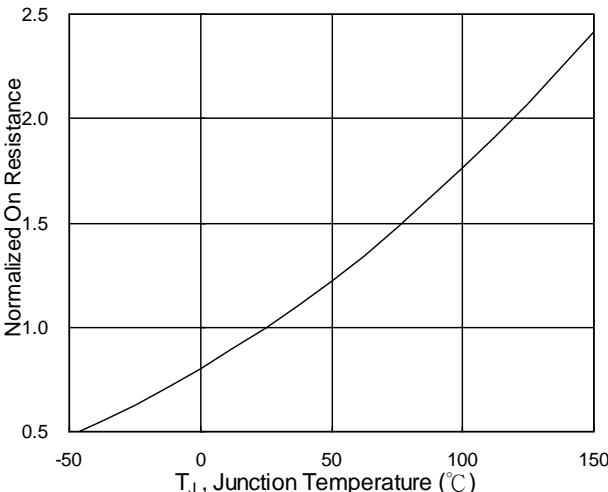
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.098	---	$^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	---	---	47	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=15\text{A}$	---	---	50	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.52	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	10	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	100	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=20\text{A}$	---	28.7	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.6	---	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	---	60	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	9.7	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	11.8	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=3.3\Omega$	---	10.4	---	$\text{ns}$
$T_r$	Rise Time		---	46	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	54	---	
$T_f$	Fall Time		---	10	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3848	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	137	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	82	---	

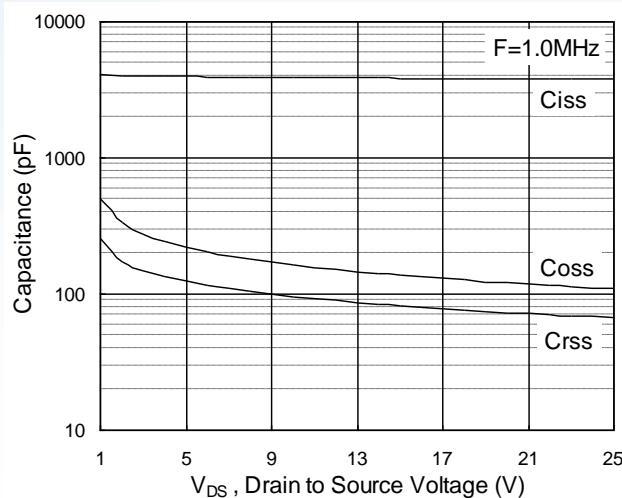
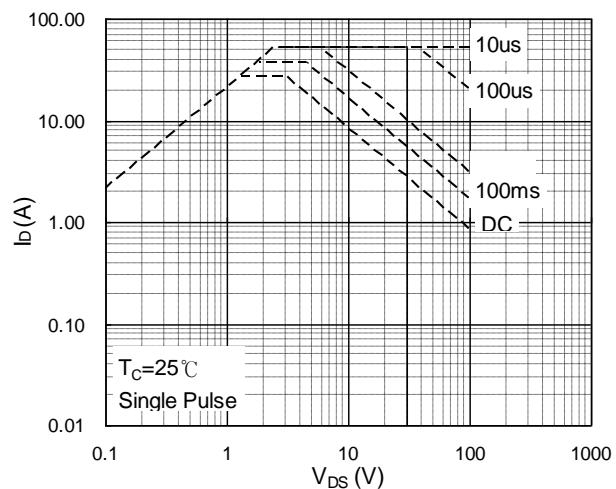
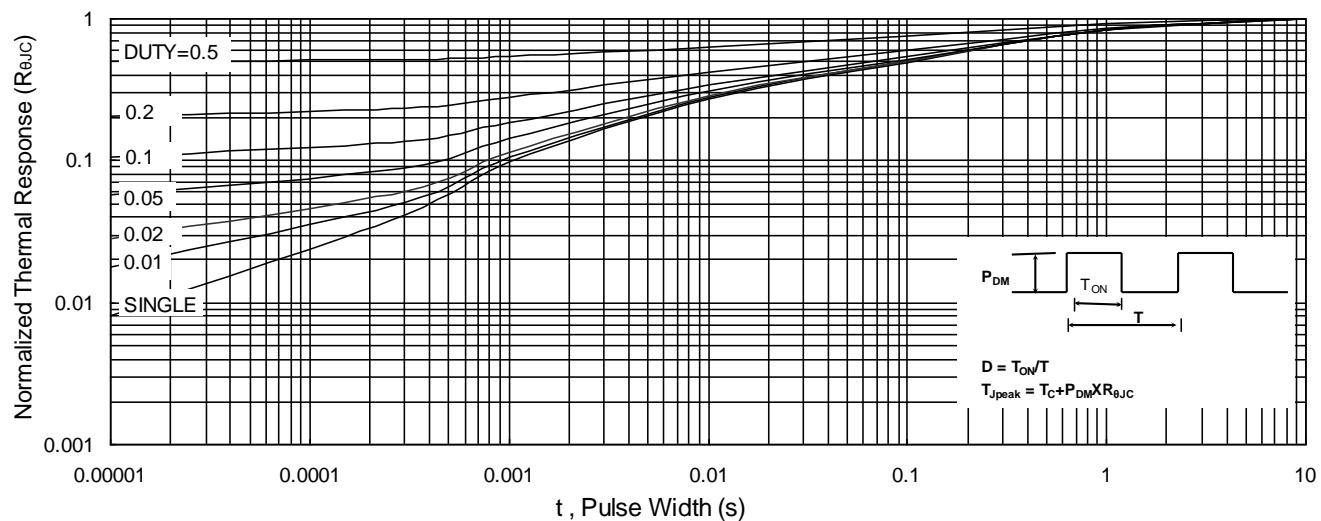
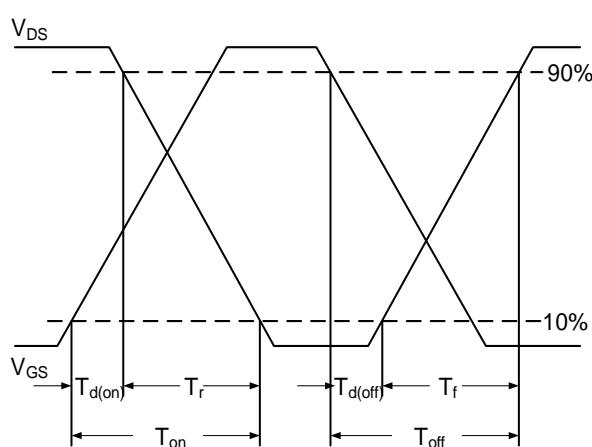
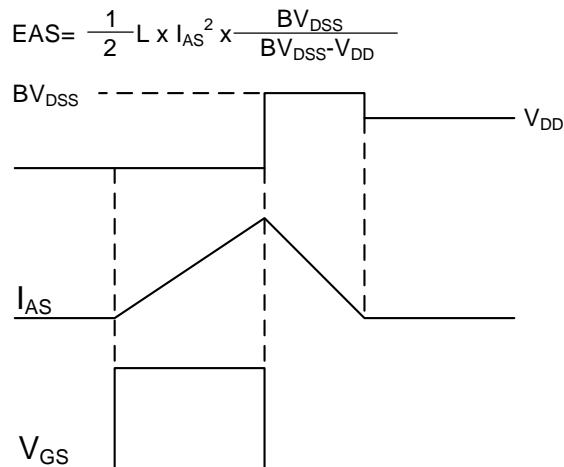
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	27	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	54	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	30	---	$\text{nS}$
$Q_{\text{rr}}$	Reverse Recovery Charge		---	37	---	$\text{nC}$

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=27\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**N-Ch 100V Fast Switching MOSFETs**
**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.3 Forward Characteristics Of Reverse**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.2 On-Resistance vs. Gate-Source**

**Fig.4 Gate-Charge Characteristics**

**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**

**N-Ch 100V Fast Switching MOSFETs**
**Fig.7 Capacitance****Fig.8 Safe Operating Area****Fig.9 Normalized Maximum Transient Thermal Impedance****Fig.10 Switching Time Waveform****Fig.11 Unclamped Inductive Switching Waveform**

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